Electronic Act	knowledgement Receipt			
EFS ID:	5298668			
Application Number:	10755042			
International Application Number:				
Confirmation Number:	8665			
Title of Invention:	Integrated chip package structure using silicon substrate and method of manufacturing the same			
First Named Inventor/Applicant Name:	Mou-Shiung Lin			
Customer Number:	27765			
Filer:	Winston Hsu			
Filer Authorized By:				
Attorney Docket Number:	MEGP0004USA1			
Receipt Date:	08-MAY-2009			
Filing Date:	09-JAN-2004			
Time Stamp:	04:17:12			
Application Type:	Utility under 35 USC 111(a)			
Payment information:				

Submitted wi	th Payment	no			
File Listin	g:				
Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (SB/08)	618746.PDF	738682	no	4

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	NPL Documents	NPL3.pdf	725052	no		
Information:						
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4 NPL Doc	NFL Documents	NFL2.FDF	a1990a68fa3e1e621fa33a6b7ffcec77afc6d b2c	no	,	
	NPL Documents	NPL2.PDF	1433670	no	7	
Information:			4 7 7 6			
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3	THE BOCKHICKS	111 (111 )	b84eccd37953b5bf2bd42c518e86a390776 9a92c	110	3	
	NPL Documents	NPL1.PDF	530067	no		
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2	roreignnerence	1w_551654.par	a2637e2d063d87f453fef9c158d502bce57b 286c	110	32	
	Foreign Reference	TW 531854.pdf	1757971	no		

Post Card, as described in MPEP 503.

### New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

# National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

## New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.